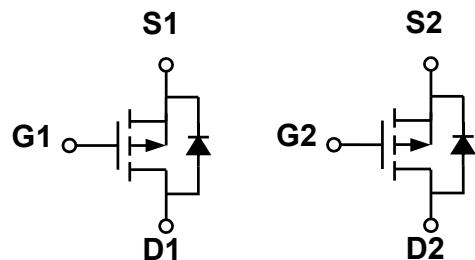
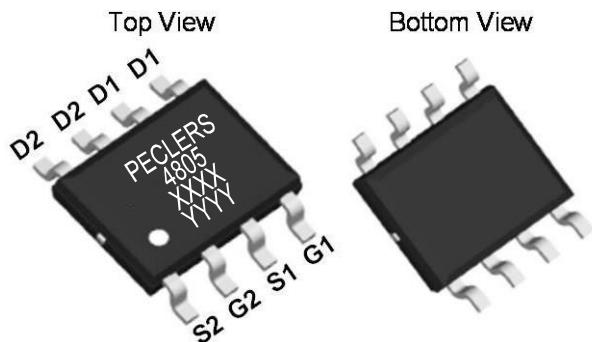


30V Dual P-Channel Enhancement Mode MOSFET**Schematic diagram****Marking and pin assignment**

XXXX—Wafer Information YYYY—
Quality Code

Description

The PECN4805SR uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

- ◆ $V_{DS} = -30V$, $I_D = -8A$
- ◆ $R_{DS(ON)}(\text{Typ.}) = 24.6\text{m}\Omega$ @ $V_{GS} = -4.5V$
- ◆ $R_{DS(ON)}(\text{Typ.}) = 18.7\text{m}\Omega$ @ $V_{GS} = -10V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

- ◆ PWM applications
- ◆ Load switch

Package

- ◆ SOP-8

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4805SR	-55°C to +150°C	SOP-8	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage	V_{GS}	± 20	V
Drain Current-Continuous (Silicon Limited)	I_D	-8	A
		-6	
Pulsed Drain Current (Package Limited)	I_{DM}	-32	A
Maximum power dissipation	P_D	2	W
		1.3	
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
		T _J =85°C	-	-	-30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.2	-1.6	-2.5	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-10V, I _D =-8A	-	18.7	20	mΩ
		V _{GS} =-4.5V, I _D =-7A	-	24.6	25	
On Status Drain Current	I _{D(ON)}	V _{DS} =-15V, V _{GS} =-10V	-8	-	-	A
Diode Characteristics						
Diode Forward Voltage	V _{SD}	I _{SD} =-8A, V _{GS} =0V	-	-0.8	-1.3	V
Diode Continuous Forward Current	I _S		-	-8	-	A
Reverse Recovery Time	t _{rr}	I _F =-8A, dI/dt=-100A/us	-	24	-	ns
Reverse Recovery Charge	Q _{rr}		-	16	-	nC
Dynamic Characteristics						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	0.65	-	Ω
Input capacitance	C _{iss}	V _{GS} =0V, V _{DS} =-15V f=1.0MHz	-	1605	-	pF
Output capacitance	C _{oss}		-	163	-	
Reverse transfer capacitance	C _{rss}		-	145	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-10V, V _{DD} =-30V, R _L =3Ω, I _D =-1A, R _G =2.5Ω	-	9	-	ns
Turn-on Rise time	t _r		-	10	-	
Turn-off delay time	t _{D(OFF)}		-	50	-	
Turn-off Fall time	t _f		-	20	-	
Total gate charge	Q _g	V _{GS} =-10V, I _D =-8A V _{DS} =-15V	-	31.8	-	nC
Gate-source charge	Q _{gs}		-	4.4	-	
Gate-drain charge	Q _{gd}		-	6.1	-	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	R _{θJA}	33	40	°C/W
Maximum Junction-to-Ambient ^A		59	75	
Maximum Junction-to-Lead ^B		16	24	

A: The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

Typical Performance Characteristics

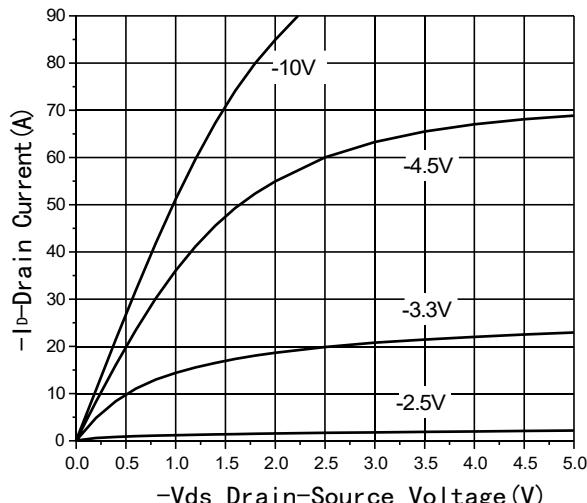


Fig1 Output Characteristics

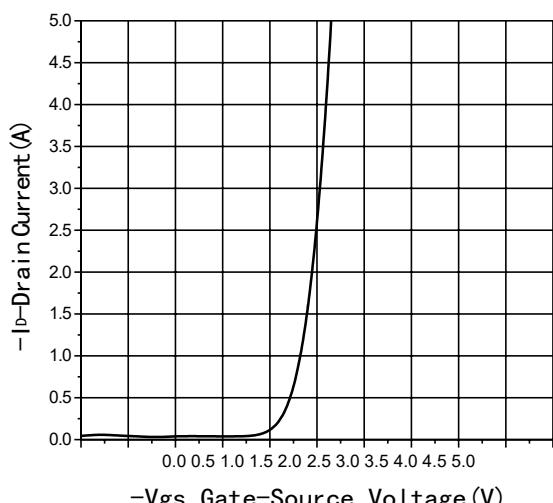


Fig2 Transfer Characteristics

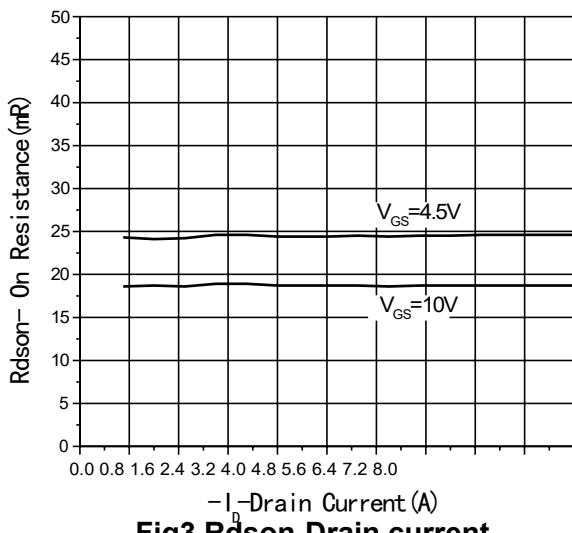


Fig3 Rdson-Drain current

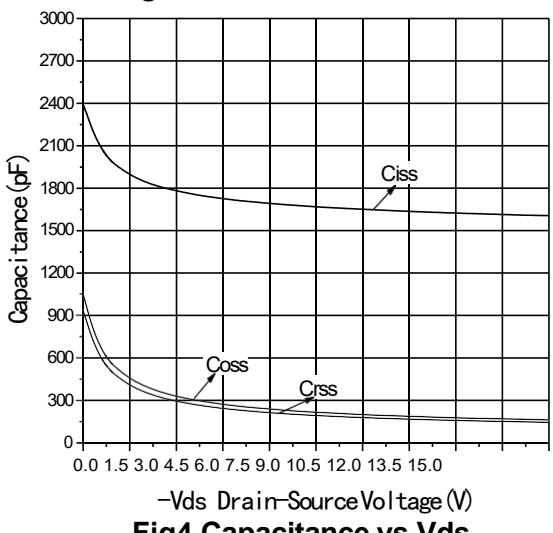


Fig4 Capacitance vs V_{DS}

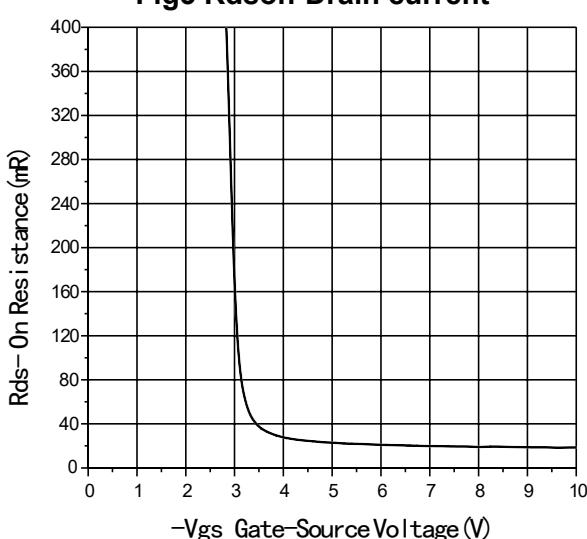


Fig5 Rdson-Gate Drain voltage

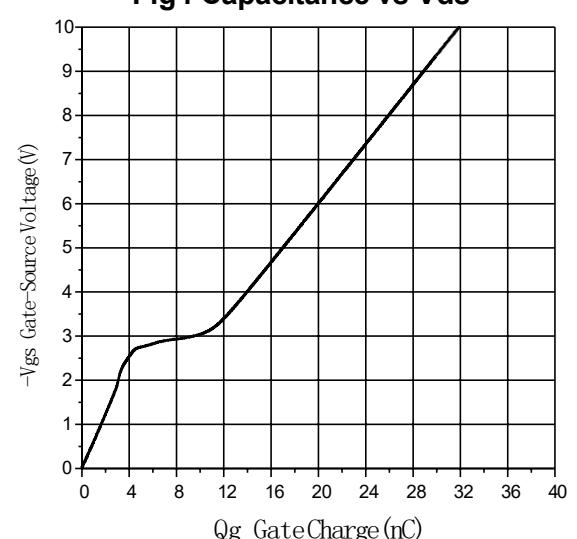


Fig6 Gate Charge

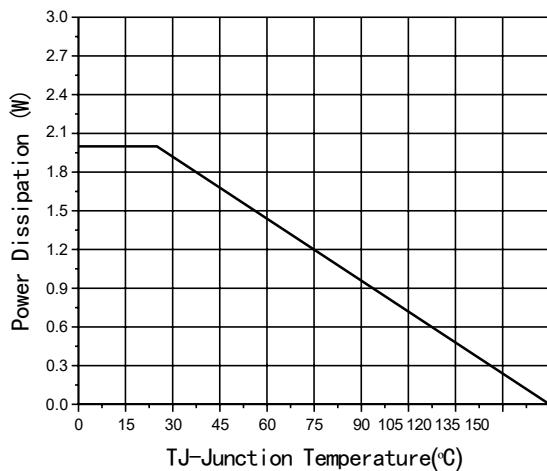


Fig7 Power De-rating

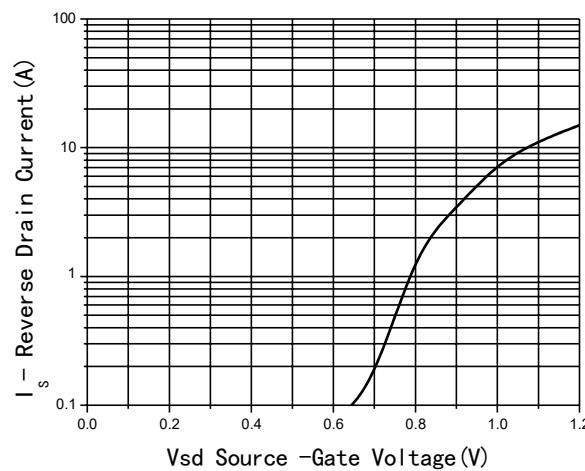


Fig8 Source-Drain Diode Forward

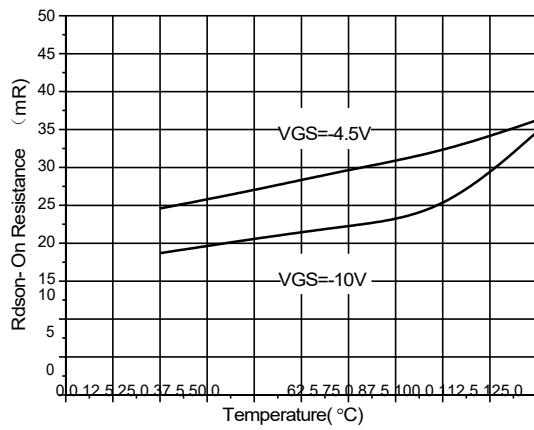


fig9 Rdson vs Junction Temperature

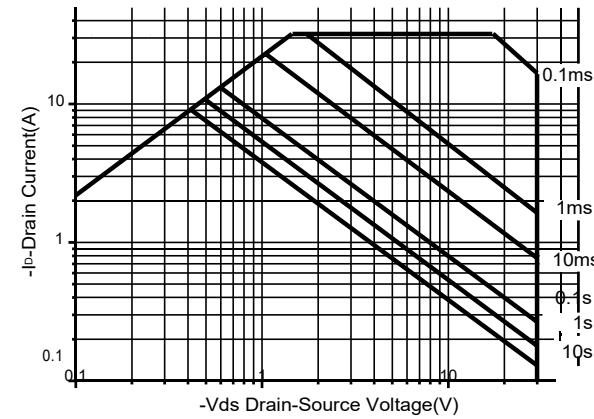


Fig10 Safe Operation Area

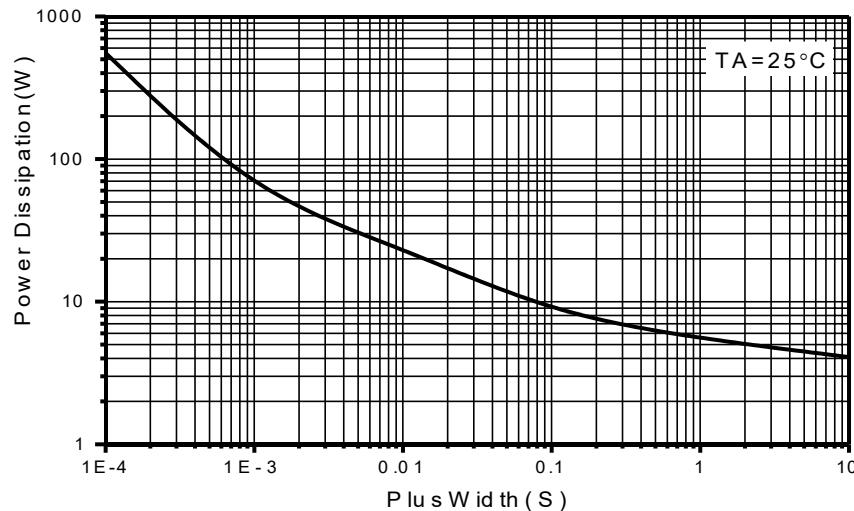
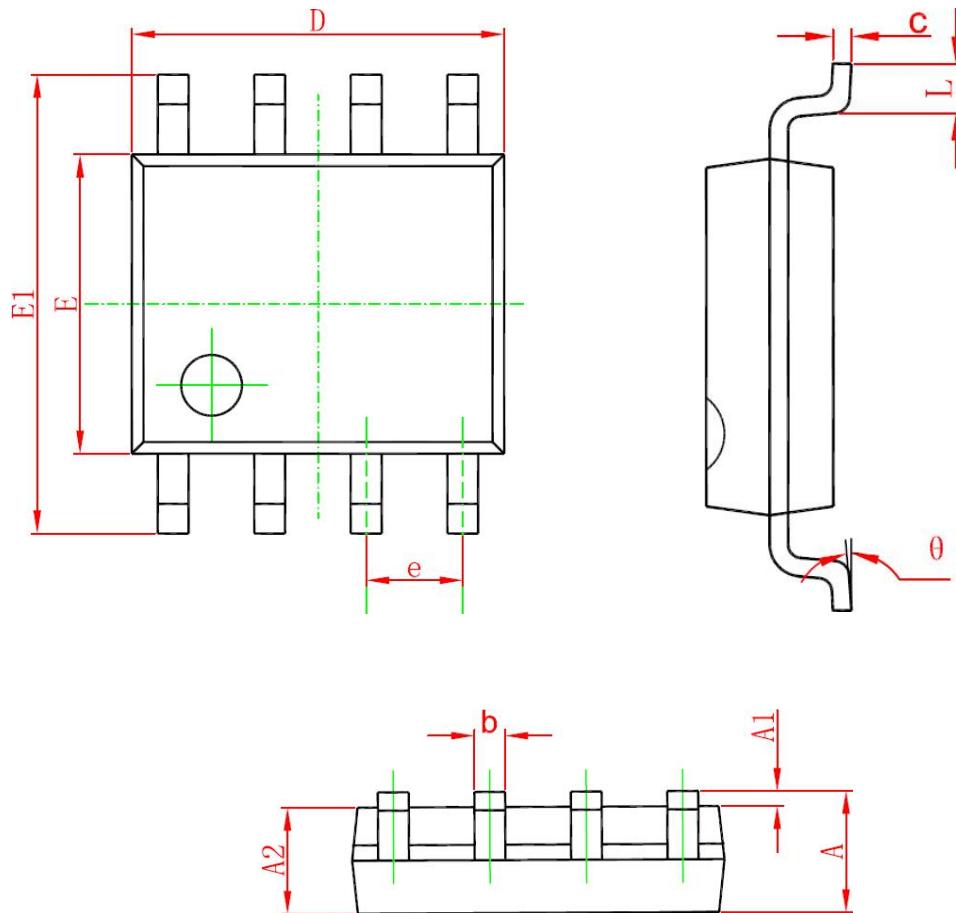


Fig11 Single Plus Power Rating Junction to Ambient

Package Information

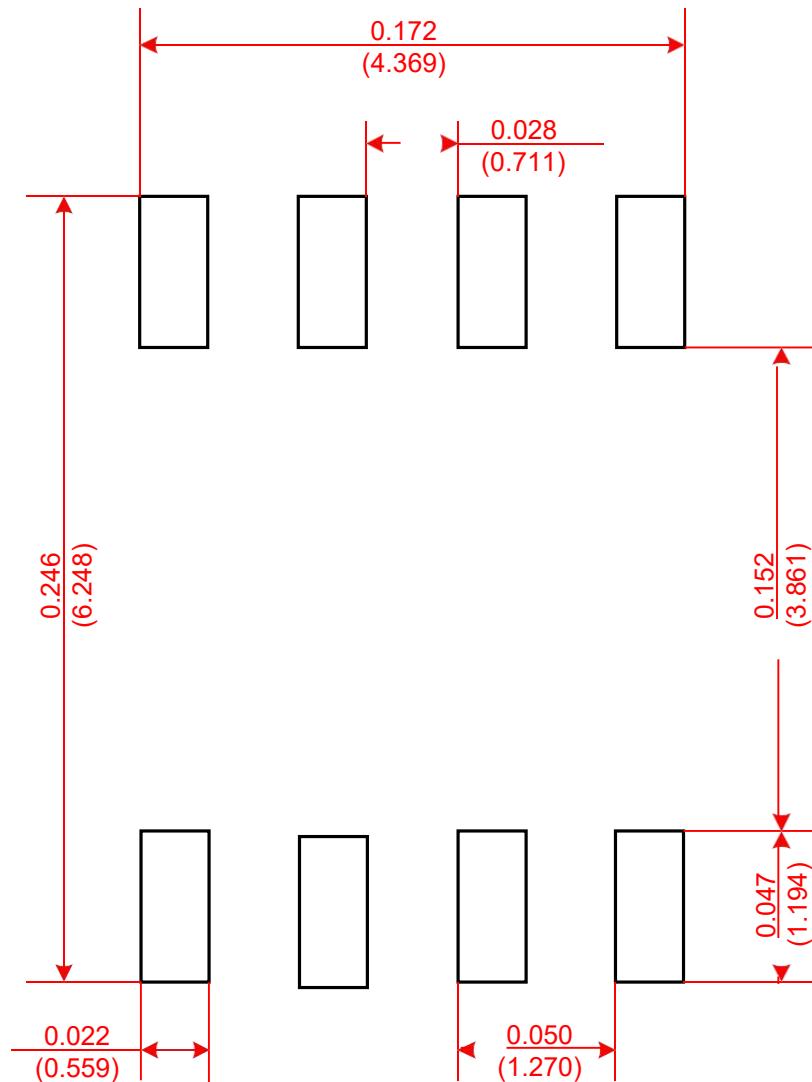
- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Recommended Minimum Pads

- SOP-8



Recommended Minimum Pads
Dimensions in Inches/(mm)